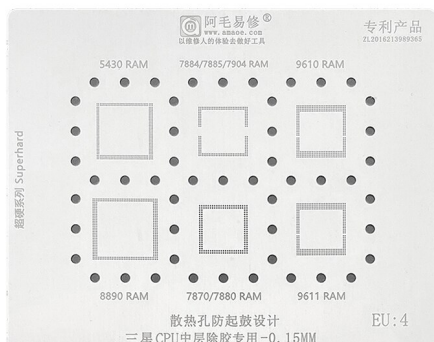


Main page > Repair Equipment > Soldering Equipment > Stencil BGA kit > BGA reballing stencil EU4v2.0 for Samsung Exynos RAM5430/7884/7885, 7904/9610/8890, 7870/7880/9611



## BGA reballing stencil EU4v2.0 for Samsung Exynos RAM5430/7884/7885, 7904/9610/8890, 7870/7880/9611

Product ID: 22850

Price: **6.00 EUR**

Product weight: **0.30 kg**

### Description:

BGA reballing stencil EU4v2.0 for Samsung Exynos RAM5430/7884/7885, 7904/9610/8890, 7870/7880/9611 reballing stencil, template, matrix for Samsung Exynos RAM chip repair.

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